Dual General Purpose Transistors

The MBT3904DW1T1G and MBT3904DW2T1G devices are a spin-off of our popular SOT-23/SOT-323 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-363 six-leaded surface mount package. By putting two discrete devices in one package, this device is ideal for low-power surface mount applications where board space is at a premium.

Features

- h_{FE}, 100-300
- Low $V_{CE(sat)}$, $\leq 0.4 \text{ V}$
- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- Available in 8 mm, 7-inch/3,000 Unit Tape and Reel
- AEC-Q101 Qualified and PPAP Capable
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|--------------------------------|------------------|---------------------------|------|
| Collector - Emitter Voltage | V_{CEO} | 40 | Vdc |
| Collector - Base Voltage | V_{CBO} | 60 | Vdc |
| Emitter - Base Voltage | V _{EBO} | 6.0 | Vdc |
| Collector Current - Continuous | Ic | 200 | mAdc |
| Electrostatic Discharge | ESD | HBM Class 2 MM Class B | |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|---|-----------------------------------|-------------|------|
| Total Package Dissipation (Note 1) T _A = 25°C | P _D | 150 | mW |
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 833 | °C/W |
| Junction and Storage Temperature Range | T _J , T _{stg} | -55 to +150 | °C |

^{1.} Device mounted on FR4 glass epoxy printed circuit board using the minimum recommended footprint.



ON Semiconductor®

http://onsemi.com

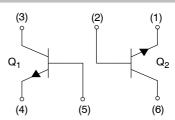


XX = MA for MBT3904DW1T1G MJ for MBT3904DW2T1G

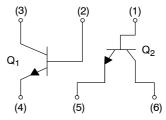
M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)



MBT3904DW1T1 STYLE 1



MBT3904DW2T1 STYLE 27

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|----------------|----------------------|-----------------------|
| MBT3904DW1T1G | SOT-363 (Pb-Free) | 3000 / Tape & Reel |
| SMMBT3904DW1TG | SOT-363 (Pb-Free) | 3000 / Tape & Reel |
| MBT3904DW2T1G | SOT-363 (Pb-Free) | 3000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

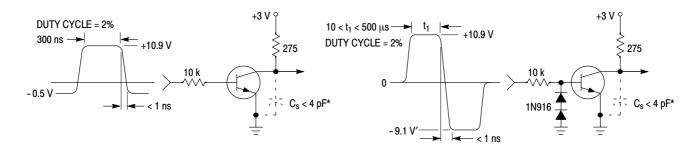
ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

| Characteristic | Symbol | Min | Max | Unit |
|--|-----------------------|-----------------------------|--------------------|--------------------|
| OFF CHARACTERISTICS | | | | • |
| Collector – Emitter Breakdown Voltage (Note 2) $(I_C = 1.0 \text{ mAdc}, I_B = 0)$ | V _(BR) CEO | 40 | - | Vdc |
| Collector – Base Breakdown Voltage ($I_C = 10 \mu Adc, I_E = 0$) | V _{(BR)CBO} | 60 | - | Vdc |
| Emitter – Base Breakdown Voltage ($I_E = 10 \mu Adc, I_C = 0$) | V _{(BR)EBO} | 6.0 | - | Vdc |
| Base Cutoff Current (V _{CE} = 30 Vdc, V _{EB} = 3.0 Vdc) | I _{BL} | - | 50 | nAdc |
| Collector Cutoff Current (V _{CE} = 30 Vdc, V _{EB} = 3.0 Vdc) | I _{CEX} | ı | 50 | nAdc |
| ON CHARACTERISTICS (Note 2) | | | | |
| DC Current Gain $ \begin{aligned} &(I_C = 0.1 \text{ mAdc, } V_{CE} = 1.0 \text{ Vdc)} \\ &(I_C = 1.0 \text{ mAdc, } V_{CE} = 1.0 \text{ Vdc)} \\ &(I_C = 10 \text{ mAdc, } V_{CE} = 1.0 \text{ Vdc)} \\ &(I_C = 50 \text{ mAdc, } V_{CE} = 1.0 \text{ Vdc)} \\ &(I_C = 100 \text{ mAdc, } V_{CE} = 1.0 \text{ Vdc)} \end{aligned} $ | h _{FE} | 40 70 100 60 30 | - 300 - - | - |
| Collector – Emitter Saturation Voltage ($I_C = 10 \text{ mAdc}$, $I_B = 1.0 \text{ mAdc}$) ($I_C = 50 \text{ mAdc}$, $I_B = 5.0 \text{ mAdc}$) | V _{CE(sat)} | 1 1 | 0.2 0.3 | Vdc |
| Base – Emitter Saturation Voltage ($I_C = 10 \text{ mAdc}$, $I_B = 1.0 \text{ mAdc}$) ($I_C = 50 \text{ mAdc}$, $I_B = 5.0 \text{ mAdc}$) | V _{BE(sat)} | 0.65 - | 0.85 0.95 | Vdc |
| SMALL-SIGNAL CHARACTERISTICS | | | | |
| Current – Gain – Bandwidth Product (I _C = 10 mAdc, V _{CE} = 20 Vdc, f = 100 MHz) | f _T | 300 | - | MHz |
| Output Capacitance (V _{CB} = 5.0 Vdc, I _E = 0, f = 1.0 MHz) | C _{obo} | - | 4.0 | pF |
| Input Capacitance (V _{EB} = 0.5 Vdc, I _C = 0, f = 1.0 MHz) | C _{ibo} | - | 8.0 | pF |
| Input Impedance ($V_{CE} = 10 \text{ Vdc}$, $I_{C} = 1.0 \text{ mAdc}$, $f = 1.0 \text{ kHz}$) | h _{ie} | 1.0 2.0 | 10 12 | kΩ |
| Voltage Feedback Ratio $(V_{CE} = 10 \text{ Vdc}, I_C = 1.0 \text{ mAdc}, f = 1.0 \text{ kHz})$ | h _{re} | 0.5 0.1 | 8.0 10 | X 10 ⁻⁴ |
| Small – Signal Current Gain (V_{CE} = 10 Vdc, I_{C} = 1.0 mAdc, f = 1.0 kHz) | h _{fe} | 100 100 | 400 400 | - |
| Output Admittance (V_{CE} = 10 Vdc, I_{C} = 1.0 mAdc, f = 1.0 kHz) | h _{oe} | 1.0 3.0 | 40 60 | μmhos |
| Noise Figure $(V_{CE} = 5.0 \text{ Vdc}, I_{C} = 100 \ \mu\text{Adc}, R_{S} = 1.0 \ \text{k} \ \Omega, f = 1.0 \ \text{kHz})$ | NF | _ _ | 5.0 4.0 | dB |

^{2.} Pulse Test: Pulse Width $\leq 300~\mu s;$ Duty Cycle $\leq 2.0\%.$

SWITCHING CHARACTERISTICS

| Characteristic | | | Min | Max | Unit |
|----------------|---|----------------|-----|-----|------|
| Delay Time | (V _{CC} = 3.0 Vdc, V _{BE} = -0.5 Vdc) | t _d | - | 35 | |
| Rise Time | (I _C = 10 mAdc, I _{B1} = 1.0 mAdc) | t _r | - | 35 | ns |
| Storage Time | (V _{CC} = 3.0 Vdc, I _C = 10 mAdc) | ts | - | 200 | |
| Fall Time | $(I_{B1} = I_{B2} = 1.0 \text{ mAdc})$ | t _f | - | 50 | ns |

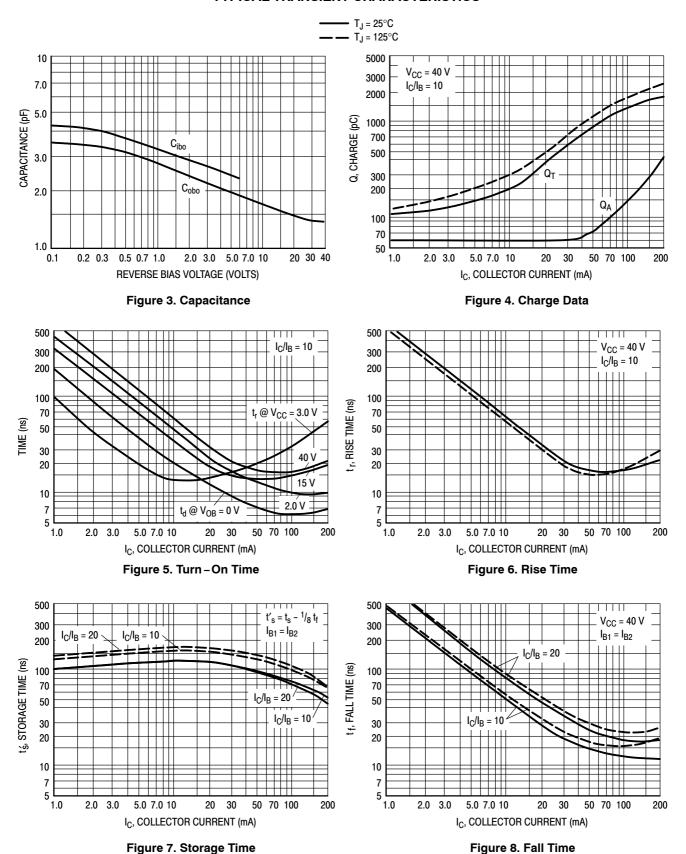


^{*} Total shunt capacitance of test jig and connectors

Figure 1. Delay and Rise Time Equivalent Test Circuit

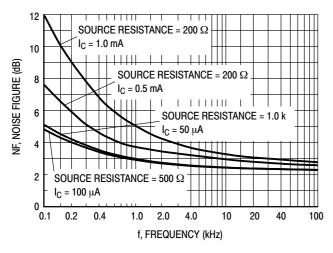
Figure 2. Storage and Fall Time Equivalent Test Circuit

TYPICAL TRANSIENT CHARACTERISTICS



TYPICAL AUDIO SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE VARIATIONS

 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}\text{C}, Bandwidth = 1.0 \text{ Hz})$



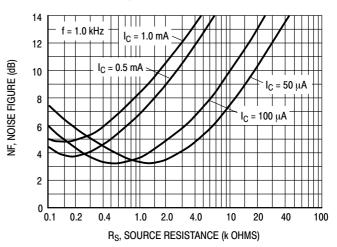
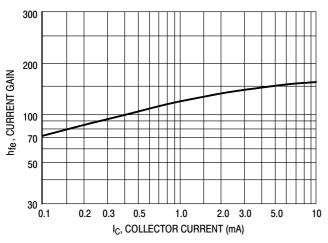


Figure 9. Noise Figure

Figure 10. Noise Figure

h PARAMETERS

 $(V_{CE} = 10 \text{ Vdc}, f = 1.0 \text{ kHz}, T_A = 25^{\circ}\text{C})$



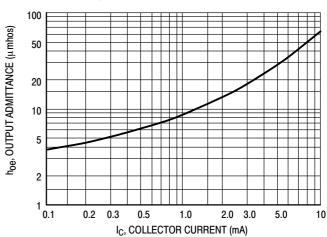


Figure 11. Current Gain

1.0 2.0 1.0 0.7 0.5

Figure 12. Output Admittance

Figure 13. Input Impedance

Figure 14. Voltage Feedback Ratio

IC, COLLECTOR CURRENT (mA)

10

, VOLTAGE FEEDBACK RATIO (x 10 -4)

0.1

TYPICAL STATIC CHARACTERISTICS

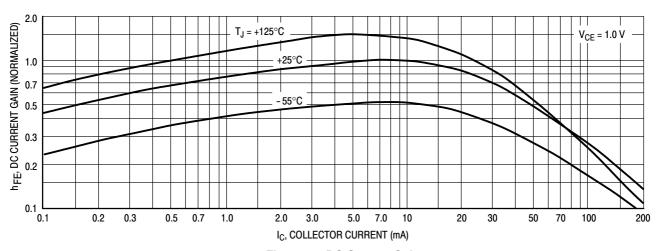


Figure 15. DC Current Gain

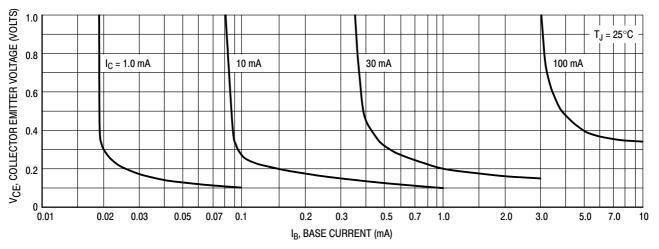


Figure 16. Collector Saturation Region

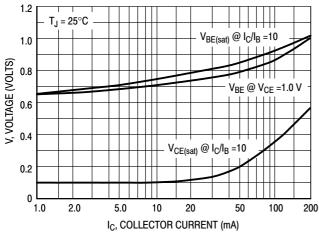


Figure 17. "ON" Voltages

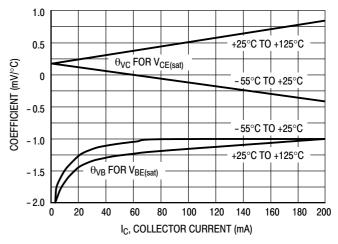


Figure 18. Temperature Coefficients

${\tt MBT3904DW1T1G,\,MBT3904DW2T1G,\,SMMBT3904DW1TG}$

TYPICAL STATIC CHARACTERISTICS

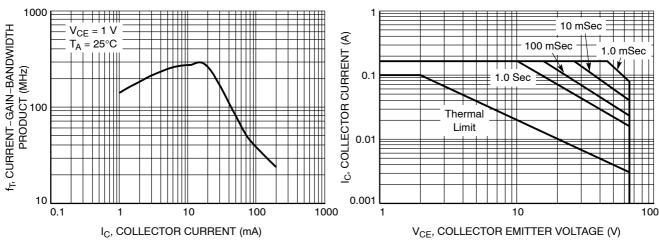
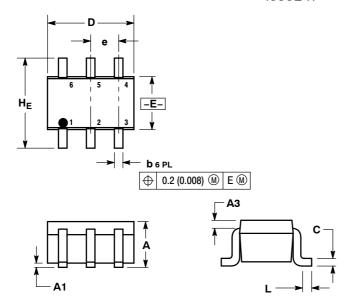


Figure 19. Current Gain Bandwidth Product

Figure 20. Safe Operating Area

PACKAGE DIMENSIONS

SOT-363/SC-88/SC70-6 CASE 419B-02 **ISSUE W**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
 - CONTROLLING DIMENSION: INCH
 - 419B-01 OBSOLETE, NEW STANDARD 419B-02.

| | MILLIMETERS | | | INCHES | | | |
|-----|-------------|----------|------|--------|-----------|-------|--|
| DIM | MIN | NOM | MAX | MIN | NOM | MAX | |
| Α | 0.80 | 0.95 | 1.10 | 0.031 | 0.037 | 0.043 | |
| A1 | 0.00 | 0.05 | 0.10 | 0.000 | 0.002 | 0.004 | |
| A3 | | 0.20 REF | | | 0.008 REF | | |
| b | 0.10 | 0.21 | 0.30 | 0.004 | 0.008 | 0.012 | |
| С | 0.10 | 0.14 | 0.25 | 0.004 | 0.005 | 0.010 | |
| D | 1.80 | 2.00 | 2.20 | 0.070 | 0.078 | 0.086 | |
| E | 1.15 | 1.25 | 1.35 | 0.045 | 0.049 | 0.053 | |
| е | | 0.65 BS | С | 0 | С | | |
| L | 0.10 | 0.20 | 0.30 | 0.004 | 0.008 | 0.012 | |
| HF | 2.00 | 2.10 | 2.20 | 0.078 | 0.082 | 0.086 | |

- STYLE 1: PIN 1. EMITTER 2 2. BASE 2
 - 3. COLLECTOR 1
 - 4. EMITTER 1

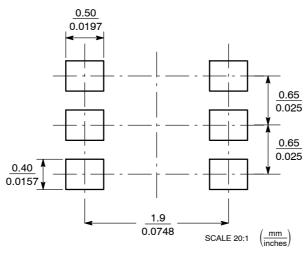
 - 6. COLLECTOR 2

STYLE 27:

- PIN 1. BASE 2 2. BASE 1
 - 3. COLLECTOR 1

 - EMITTER 1 EMITTER 2
 - 6. COLLECTOR 2

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice on semiconductor and war engineer trademarks of semiconductor components industries, Ite (SciLLC) solitate services are injective to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA

Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center

Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative